



Material Content Data Sheet



Halogen-Free

Sales Product Name	AIKP20N60CT	Issued	24. June 2021
MA#	MA002753848		
Package	PG-TO220-3-1	Weight*	2036.92 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.062	0.05	0.05	522	522
chip_2	inorganic material	silicon	7440-21-3	2.028	0.10	0.10	996	996
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		401	
	non noble metal	copper	7440-50-8	815.335	40.05	40.10	400277	400798
wire	non noble metal	aluminium	7429-90-5	6.991	0.34	0.34	3432	3432
encapsulation	inorganic material	zinc oxide	1314-13-2	5.951	0.29		2921	
	miscellaneous	miscellaneous	-	23.803	1.17		11686	
	plastics	epoxy resin	-	89.260	4.38		43821	
	inorganic material	silicon dioxide	60676-86-0	476.056	23.37	29.21	233713	292141
lead finish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10537	10537
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.069			34	
	noble metal	silver	7440-22-4	0.086			42	
	non noble metal	lead	7439-92-1	3.278	0.16	0.16	1609	1685
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		290	
	non noble metal	copper	7440-50-8	589.466	28.94	28.98	289391	289768
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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